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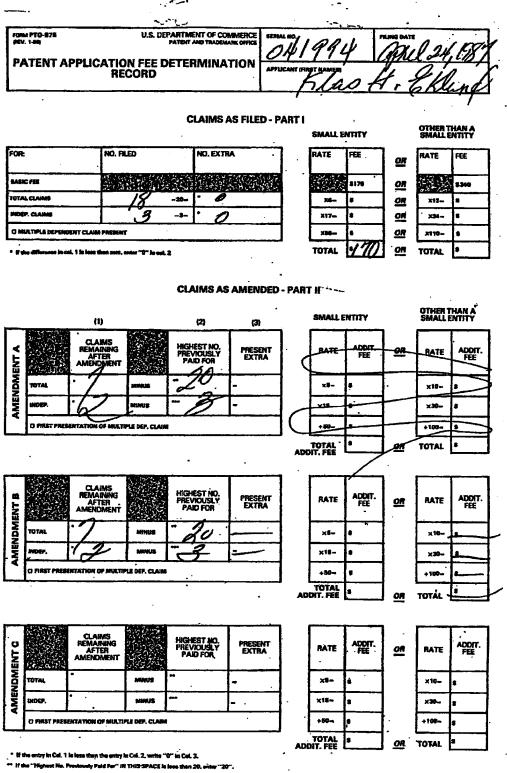
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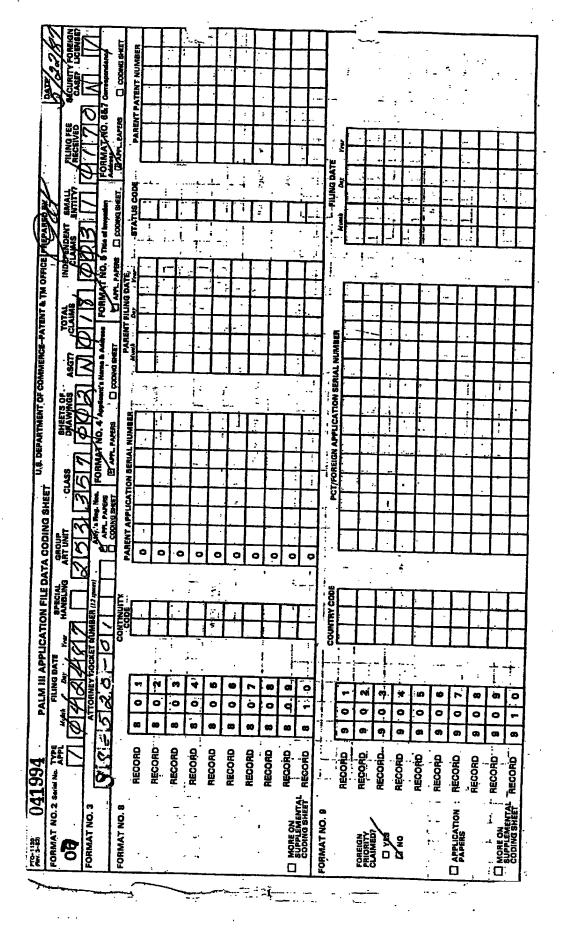
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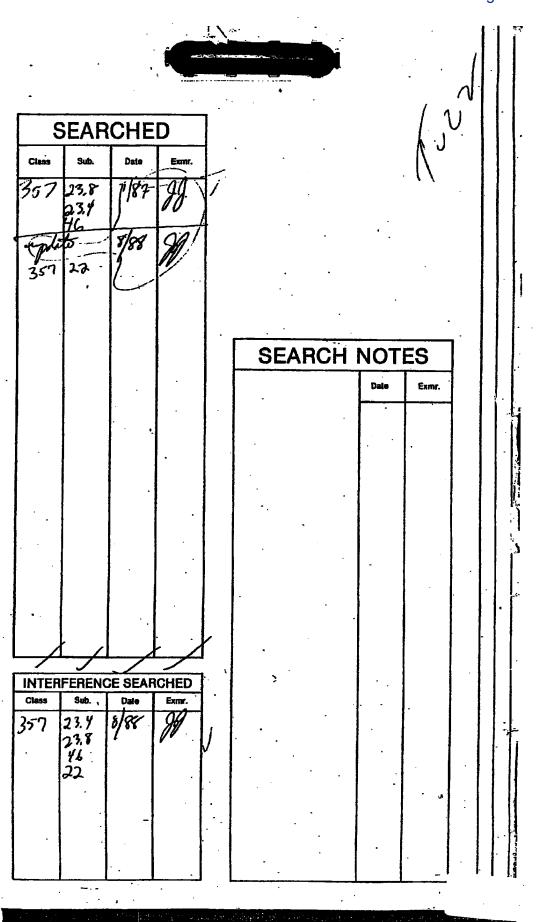
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Case Docket No. SS-520-01

Date April 20, 1987

THE COMMISSIONER OF FATENTS AND TRADEMARKS Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the patent application of:

Inventor: Klas H. Eklund

For:

HIGH VOLTAGE MOS TRANSISTORS

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Law Offices of THOMAS E. SCHATZEL A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, CA 95054 (408) 727-7077



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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

To the Commissioner of Patents and Trademarks:

Your petitioner, KLAS H. EKLUND, a citizen of Finland and resident of Los Gatos, California, whose post office address is 243 Mistletce Road, 95030, prays that letters patent may be granted to him for

BIGH VOLTAGE HOS TRANSISTORS

set forth in the following specification.

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High Voltage MOS Transistors

BACKGROUND OF THE INVENTION

Field of the Invention

This invention relates generally to high voltage metal-oxide semiconductor (MOS) transistors of the field-effect type. More specifically, the transistors can be made as either discrete or integrated devices of either n-channel or p-channel conductivity. The integrated devices can easily be combined with low voltage control logic on the same chip. Further devices of opposite conductivity can be combined in a complementary manner on the same chip.

Description of the Prior Art

Self isolation technology is used for making high voltage MOS devices, particularly integrated high voltage devices in combination with low voltage control logic on the same chip. The voltage is sustained by an offset gate, as a lightly doped extended drain region is used. Such devices can be considered as an IGFET or MOSFET in series with a single sided JFET. Two of such high voltage devices having opposite conductivity types can be used as a complementary pair of the same chip, with the device having an extended p-type drain being imbedded in an n-well in a p-substrate.

The voltage capability of such high voltage devices is determined by the doping of the substrate, the length of the extended drain region and the net number of charges therein. For optimum performance,

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the net number of charges should be around 1x1012/cm2. Such devices have been used for making display drivers in the one hundred to two hundred volt range, but the current capabilities of the devices are poor. The main advantage is that low voltage control logic easily can be combined on the same chip. For these devices, a general figure of merit can be determined by the product of RonxA (where Ron is the on-resistance in the linear region and A is the area taken up by the device). For an n-channel device in the voltage range of two hundred fifty to three hundred volts, RonxA is typically 10 - 150 mm². A discrete vertical D-MOS device in the same voltage range has a figure of merit of $3\Omega \, mm^2$, but is much more difficult to combine with low voltage control logic on the same chip. Thus, the application of these high voltage devices is restricted to current level below 100 mA, such as display drivers. Even such drivers are more costly due to poor area efficiency of the high voltage

SUMMARY OF THE PRESENT INVENTION

An object of the present invention is to provide a more efficient high voltage MOS transistor.

Another object of the invention is to provide a high voltage MOS transistor that is compatible with five volt logic.

A further object of the invention is to provide a three hundred volt n-channel device with a figure of merit, $R_{\rm on}$ x A, of about 2.0 Ω mm²,

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Briefly, the present invention includes an insulated gate, field-effect transistor (IGFET or MOSFET) and a double-sided junction gate field-effect transistor (JFET) connected in series on the same chip to form a high voltage MOS transistor. In a preferred embodiment of the invention, a complementary pair of such high voltage MOS transistors having opposite conductivity type are provided on the same chip.

Advantages of the invention include more efficient high voltage MOS transistors, compatibility with five volt logic, and for an n-channel device, voltage capability of three hundred volts with a figure of merit, $R_{\rm OR} \times A_{\star}$ of about 2.0 Ω mm².

These and other objects and advantages of the present invention will no doubt become obvious to those of ordinary skill in the art after having read the following detailed description of the preferred embodiments which are illustrated in the various drawing figures.

IN THE DRAWINGS

Fig. 1 is a diagrammatic view of a high voltage MOS transistor of the n-channel type embodying the present invention.

Fig. 2 is a diagrammatic view of a high voltage MOS transistor of the p-channel type embodying the present invention.

Fig. 3 is a diagrammatic view of the transistors shown in Figs. 1 and 2 forming a complementary pair on the same chip.

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Pig. 4 is a diagrammatic view of low voltage, C-MOS implemented devices that can be combined on the same chip with the complementary pair of high voltage MOS transistors shown in Fig. 3.

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Fig. 5 is a diagrammatic view of a symmetric high-voltage n-channel device wherein the source region and the drain region are similar.

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DESCRIPTION OF THE PREFERRED EMBODIMENT

Looking now at Fig. 1, an n-channel type, high voltage MOS transistor, indicated generally by reference numeral 10, is formed on a p-substrate 11 covered by a silicon dioxide layer 12. A metal source contact 14 and a metal drain contact 16 extend through the silicon dioxide layer to the substrate. A polysilicon gate 17 is positioned between the source contact and the drain contact at a location where the silicon dioxide layer is very thin so that the gate is slightly offset and insulated from the substrate. The polysilicon gate is the gate electrode, and an insulation layer 18 covers the gate and the silicon dioxide layer.

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Beneath the source contact 14, a pocket 19 of p⁺ material and a pocket 21 of n⁺ material are diffused into the p⁻ substrate 11. The pocket 21 extends from beneath the source contact to the gate 17. Beneath the gate is a threshold voltage implant 22 of p-type material for adjusting the threshold voltage and a punch through implant 23 of p-type material for avoiding punch through voltage breakdown. Beneath the drain contact 16, a pocket 24 of n⁺ material is diffused into the substrate. An

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extended drain region 26 of n-material is formed by diffusion or ion implantation on top of the p-substrate, and extends from beneath gate 17 to the pocket 24 and a similar distance to the opposite side of the pocket. A top layer 27 of p- material is provided by ion-implantation through the same mask window as the extended drain region to cover an intermediate portion thereof, while the end portions of the drain region are uncovered to contact the silicon dioxide layer 12. The top layer is either connected to the substrate or left floating.

The gate 17 controls by field-effect the current flow thereunder laterally through the p-type material to the n-type material in the extended drain region 26. Further flow through the extended drain region can be controlled by the substrate 11 and the top layer 27, which act as gates providing field-effects for pinching off the extended drain region therebetween. Thus, the transistor 10 can be considered as an insulated gate, field-effect transistor (IGFET or MOSPET) connected in series with a double-sided, junction-gate field-effect transistor (JFRT). While the insulated gate, field-effect transistor shown is a conventional MOS type, it should be understood that it could also be a lateral D-MOS or a depletion MOS type.

By adding the top layer 27 over the extended drain region 26 and connecting this top layer to the substrate 11, the net number of charges in the extended drain, region can be increased from $1 \times 10^{12}/\text{cm}^2$ to around $2 \times 10^{12}/\text{cm}^2$, or approximately double. This drastically reduces the on-resistance of the transistor 10. The pinch off

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voltage of the extended drain region can be reduced from typically around forty volts to below ten volts. Thus, a conventional short channel, thin gate oxide MOS transistors can be used as the series transistor instead of a D-MOS device. This results in the following benefits. First, the threshold voltage of a conventional MOS transistor is typically much lower than for a D-MOS device (0.7 volts compared to two four volts for the D-MOS device) and thus, is directly compatible with five volt logic. The D-MOS device usually requires an additional power supply of ten to fifteen volts for driving the gate. Second, the conventional MOS transistor has less on resistance and thus, further reduces the total on registance.

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As the p-type top layer 27 can be made very shallow with a depth of one micron or less, the doping density in that layer will be in the range of $5 \times 10^{16} - 1 \times 10^{17}/\text{cm}^3$. At doping levels above $10^{16}/\text{cm}^3$, the mobility starts to degrade and a decrease in mobility will increase the critical electrical field for breakdown, thus giving a higher breakdown voltage for fixed geometry. The number of charges in the top layer is around $1 \times 10^{12}/\text{cm}^2$ and to first order approximation independent of depth.

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The combined benefits of the above features result in a voltage capability of three hundred volts with a figure of merit, $R_{\rm OR}$ x A, of about $2.0~\Omega$ mm² for the transistor 10. Currently used integrated MOS transistors have a figure of merit of about $10-15~\Omega$ mm², while the best discrete vertical D-MOS devices on the market in a similar voltage range have a figure of merit of $3-4~\Omega$ mm².

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With reference to Fig. 2, a p-channel type, high voltage MOS transistor is indicated generally by reference numeral 30. Since the layers of substrate, silicon dioxide, and insulation for this transistor are similar to those previously described for transistor 10, they will be given like reference numerals. A p-substrate 11 is covered by a silicon dioxide layer 12 and an insulation layer 18. A metal source contact 31 and a metal drain contact 32 extend through the insulation layer and the silicon dioxide layer to an n-well 33 that is embedded in the substrate. A polysilicon gate 34, which is an electrode, is positioned between the source contact and the drain contact at a location where the silicon dioxide layer is very thin so that the gate is slightly offset and insulated from the n-well. The gate and the silicon dioxide layer are covered by the insulation layer 18.

A pocket 35 of n⁺ type material and a pocket 36 of p⁺ type material are provided in the n-well 33 beneath the metal source contact 31. The pocket 36 extends to the gate 34. An extended drain region 37 of p-type material is formed in the n-well and extends from beneath the gate to a pocket 38 located beneath the drain contact 32, and the extended drain region continues a similar distance on the opposite side of the drain contact. A top layer 39 of n-material is provided by ion-implantation through the same window of the mask as the extended drain region to cover an intermediate portion thereof. The end portions of the extended drain region are uncovered so as to contact the silicon dioxide layer 12. The top layer is either connected to the n-well or left floating.

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The gate 34 controls by field-effect the current flow thereunder laterally through the n-type material to the p-type material in the extended drain region 37. Further flow through the extended drain region can be controlled by the n-well 33 and the top layer 39, which act as gates providing field-effects for pinching off the extended drain region therebetween. Thus, the transistor 30 can be considered as an insulated-gate field-effect transistor (IGFET or MOSFET) connected in series with a double-sided, junction-gate field-effect transistor (JFET). The n-well under the extended drain region has to be depleted before breakdown occurs between the p + drain contact pocket 38 and the n-well.

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Looking now at Fig. 3, an n-channel transistor 10, similar to that shown in Fig. 1, and a p-channel transistor 30, similar to that shown in Fig. 2, are shown as a complementary pair on the same substrate 11 and isolated from each other. Since the details of each transistor has been previously described with reference to Figs. 1 and 2, no further description is considered necessary.

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As shown in Fig. 4, low voltage, C-MOS implemented devices 43 and 44 can be combined on the same p-substrate 11 as the high voltage devices 10 and 30, shown in Fig. 3. These low voltage devices enable low voltage logic and analog function to control the high voltage devices. The device 43 is an n-channel type having a source contact 46, a drain contact 47 and a polysilicon gate 48. A p⁺ pocket 49 and an n⁺ pocket 51 are provided in the p⁻ substrate beneath the source contact. The n⁺ pocket extends to beneath the gate. An n⁺ pocket 52 is provided

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beneath the drain contact. The gate 48 is insulated from the substrate by the silicon dioxide layer 12, but the gate controls the current flow through the substrate between pockets 51 and 52. The gate is covered by the insulation layer 18. An n-well 53 is -provided in the substrate to accommodate the low voltage, p-channel device 44. This device includes a source contact 54, a drain contact 56 and a polysilicon gate 57. An n+ pocket 58 and a p+ pocket 59 are provided in the n-well beneath the source contact and a p+ pocket 61 is provided in the n-well beneath the drain contact. The gate 57 is insulated from the n-well and extends thereabove between pockets 59 and 61.

Fig. 5 shows a symmetrical n-channel device 63

having a source contact 64 and a drain contact 66. A polysilicon gate 67 is insulated from a substrate 68 by a silicon dioxide layer 69 and the gate is covered by an insulation layer 20. An n-type extended source region 71 is provided beneath the source contact and an n+ type pocket 72. A top layer 73 of p-type material is positioned over an intermediate portion of the extended source region, while the end portions of the extended source region contact the silicon dixode layer thereabove. Beneath the drain contact is an n+ type pocket 74 and an n-type extended drain region 76. A top layer -72 of p-type material is positioned over an intermediate portion of the extended drain region and end portions of the extended drain region contact the silicon dioxide layer. An

implant 78 of the p-type material is provided under the gate 67 between the extended source region and the extended drain region for sustaining the threshold voltage. A similar implant 79 for sustaining the

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punch-through voltage is provided beneath the implant 78. Since the symmetrical channel device has both an extended source an an extended drain, the source can sustain the same high potential as the drain. A symmetric p-channel device could be made in a similar way using opposite conductivity type materials.

From the foregoing description, it will be seen that an efficient, high voltage MOS transistor has been provided. This transistor is compatible with five wolt logic which easily can be integrated on the same chip. The transistor has a voltage capability of three hundred volts for an n-channel device, and has a figure of merit, $R_{on} \times A$, of about 2.0 Ωmm^2 . The transistor is formed by an insulated-gate field-effect transistor and a double-sided junction-gate field-effect transistor connected in series on the same chip. These transistors can be made as either discrete devices or integrated devices of either n-channel or p-channel conductivity. The integrated devices can be easily combined with low voltage control logic on the same chip. Further devices of opposite conductivity can be combined in a complementary manner on the same chip.

Although the present invention has been described in terms of the presently preferred embodiment, it is to be understood that such disclosure is not to be interpreted as limiting. Various alterations and modifications will no doubt become apparent to those of ordinary skill in the art after having read the above disclosure. Accordingly, it is intended that the appended claims be interpreted as covering all

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alterations and modifications as fall within the true spirit and scope of the invention.

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IN THE CLAIMS

- A high-voltage MOS transistor comprising an insulated-gate field-effect transistor, and a double-sided junction-gate field-effect transistor connected in series, said transistors being united/in one structure.
- In a high-voltage MOS transistor paving a source, a drain, an insulated gate device for controlling current flow between the source and the drain, an extended drain region in secies between the insulated-gate device and the drain, said extended drain region being formed on material having a conductivity-type opposite that of the extended drain region, and wherein the improvement comprises a layer of material on top of the extended drain region having a conductivity-type opposite that of the extended. drain region, and wherein the improvement comprises a layer of material on top of the extended drain region having a conductivity type opposite that of the extended drain region, said top layer of material and said material beneath the extended drain region being interconnected with the source for applying a reverse-bias voltage whereby current flow through the extended drain region can be pinched off by depletion from both sides adjacent the opposite conduct/vity-type materials.
 - A high-voltage MOS transistor comprising a source, a drain, an insulated gate device for controlling current flow between the source and the dwain, an extended drain region in series between the insulated gate device and the drain, said extended grain region being formed on material having a

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conductivity-type opposite that of the extended drain region, and a layer of material on top of the extended drain region having a conductivity-type opposite that of the extended drain region, said top layer of material and said material beneath the extended drain region being interconnected with the source for applying a reverse-bias voltage whereby current flow through the extended drain region can be pinched off by depletion from both sides adjacent the opposite conductivity-type materials.

4. The bigh-voltage MOS transistor of claim 1 further including,

another high-voltage MOS transistor of opposite conductivity-type forming a complementary pair on the same chip.

5. The high-voltage MOS transistor of claim 2 wherein,

said layer on top of the extended drain
region is an ion-implantation.

The high-voltage MOS transistor of claim & f

said top layer has a depth of one-micron or less.

**.3 The high-voltage MOS transistor of claim \$ 47

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said top layer has a doping density higher than 5 x 10^{16} /cm³ so that the mobility starts to degrade.

8. The high-voltage MOS transistor of claim 3 5 . wherein,

said extended drain is made of n-type conductive material and said top layer is made of p-type conductive material.

The high-voltage MOS transistor of claim 3 wherein,

said extended drain is made of p-type conductive material and said top layer is made of n-type conductive material.

10. The high-voltage OS transistor of claim wherein,

said transfistor is embedded in a well of n-type conductive material in a substrate of p-type conductive material, and further including a complementary high-voltage MOS transistor having an extended drain of n-type conductive material embedded in the substrate.

The high-voltage MOS transistor of claim 3 11. wherein,

both the extended drain region and the top layer of material are diffusions or ion implantations into a substrate or epitaxial layer.

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12. The high-voltage MOS transistor of claim wherein,

said extended drain region and the top layer of material are formed by using the same mask (self alignment).

13. The high-voltage MOS transistor of claim 3 wherein,

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the material on which the extended drain region is formed is a substrate; and

the substrate is of one conductivity-type
15 material, and further including a complementary
transistor embedded in a well or epi-island of
opposite conductivity-type material on the same
substrate.

14. The complementary pair of high-voltage MOS transistors of claim 13 wherein,

the well in which the complementary transistor is embedded is the same diffusion as the extended drain for the other transistor.

15. The complementary pair of high-voltage MOS transistors of claim 14 wherein,

the well is an n-well and further used for a low voltage p-channel device.

6. The high-voltage MOS transistor of claim 2 wherein,

the top layer is floating.

17. The high-voltage MOS transistor of claim 3 wherein,

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region and the drain region are similar manner. formed in a

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he Migh-voltage MOS transistor of claim 3

low voltage logic and analog function on the

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ABSTRACT OF THE DISCLOSURE

An insulated-gate, field-effect transistor and a double-sided, junction-gate field-effect transistor are connected in series on the same chip to form a high-voltage MOS transistor. An extended drain region is formed on top of a substrate of opposite conductivity-type material. A top layer of material having a conductivity-type opposite that of the extended drain and similar to that of the substrate is provided by ion-implantation through the same mask window as the extended drain region. This top layer covers only an intermediate portion of the extended drain which has ends contacting a silicon dioxide layer thereabove. The top layer is either connected to the substrate or left floating. Current flow through the extended drain region can be controlled by the substrate and the top layer, which act as gates providing field-effects for pinching off the extended drain region therebetween. A complementary pair of such high-voltage MOS transistors having opposite conductivity-type are provided on the same chip.

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As a below	named inventor, I	hereby declare that:	•
. Hy residenc my name,	e, post office ad	dress and citizenship are	as stated below next to
	m original, lir. Dject matter which	first and sole inventor (st and joint inventor (if h is claimed and for which	
	RIGH.	VOLTAGE HOS TRANSISTORS	
the specification	n of which		
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I acknowledg examination of t Regulations, \$1.	ura abbiicaryon it	lose information which is a accordance with Title 37	material to the , Code of Federal
I hereby ap application and connected therew	to classacc wit bi	g attorney(s) and/or agent siness in the Patent and	Trademark Office
	Thomas E. Schatz Douglas R. Mille	el Reg. No. 22.611	0(
Address all (408) 727-7077.	telephone calls t	o Thomas E. Schatzel at to	elephone No.
Address all	correspondence to	•	
	A Professions	F THOMAS E. SCHATZEL 1 Corporation ulevard, Scize 2010 California 95054-3093	
	Saportis.	California 95054-3093	•
and have also ide	entified below and	y benefits under Title 35, for patent or inventor's foreign application for p efore that of the applicat	certificate listed below
rior Foreign App	olication(s)		Priority Claimed
	•		1110110) Olalieu
(Number)	(Country)	(Day/Month/Year Filed)	Yes No
(Kumber)	(Country)	(Day/Month/Year Filed)	Yes No
(Number)	(Country)	(Day/Month/Year Filed)	Yes No

I hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and, insofar as the subject matter to each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, \$112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, \$1.56(a) which occurred between the filling date of the prior application and the national or PCT international filling date of this application:

(Application Serial No.)

(Filing Date)

(Status: patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status: patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are pumishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor:

Inventor's Signature:

Date:

243 Mistletoe Road Los Gatos, California 95030

Citizenship: Finland

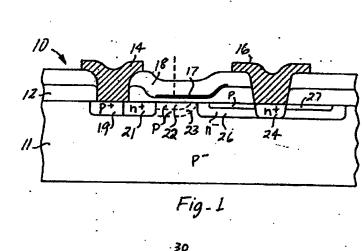
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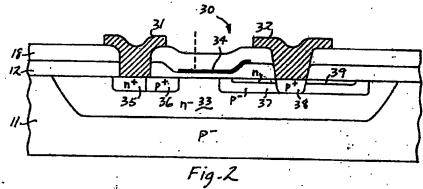
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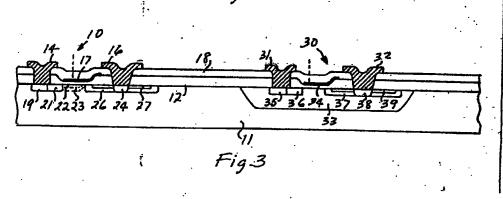
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Applicant or Patentee Serial or Patent No.:	KLAS R. EKLUND	Attorney's
Filed or Issued:		Docket No.: 520-03
For:	HIGH VOLTAGE MOS TRA	NSISTORS
VERIFIED (37	STATEMENT (DECLARATION) CLAIMING CFR 1.9(f) and 1.27(c) - INDEP	OF CHAIL PUTITY CTAMES
	entor, I hereby declare that I of 1.9(c) for purposes of paying to united States Code, to the Patton entitled <u>HIGH VOLTAGE</u>	qualify as an independent inventor reduced fees under section 41(s) and and Trademark Office with MOS TRANSISTORS
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KLAS H. EKLUND

55-520-01

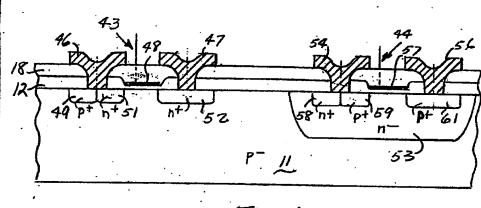


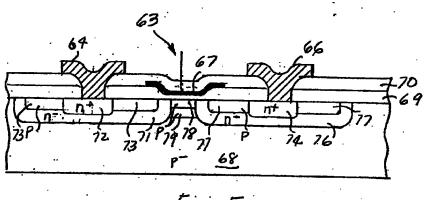


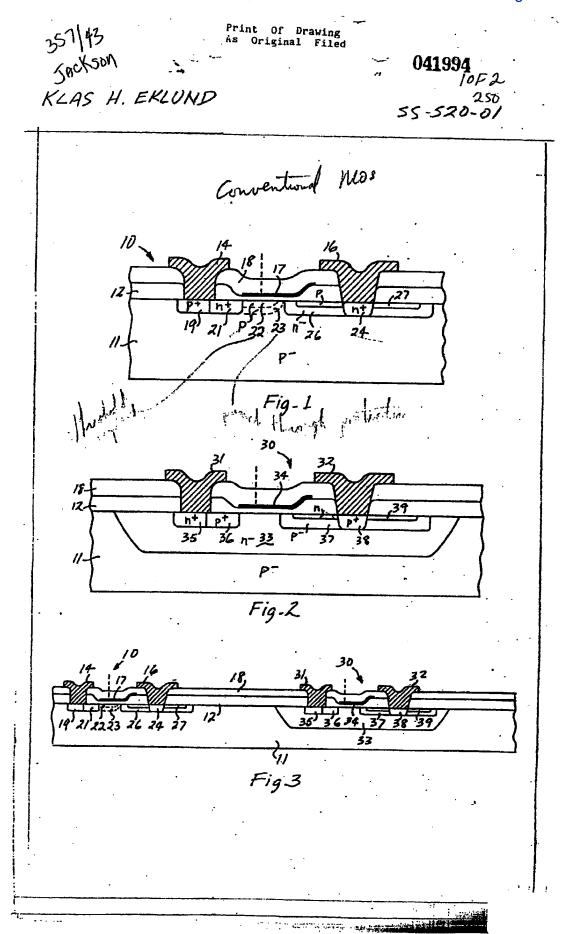


KLAS H. EKLUND

55-520-01







Print Of Drawing As Original Filed 041994 KLAS H. EKLUND 66

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				ART UNIT	PAPER NUMBER
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-		•		DATE MAILED:	12/07/87

		This is a communication from the examiner in charge of your application.	
		COMMISSIONER OF PATENTS AND TRADEMARKS	
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	fhis a	application has been examined Responsive to communication filed on] This action is made time!.
A sh	orten	>	
Fait	re to	respond within the period for response will cause the application to become abandood. 35 U.S.C. 13	e date of this letter. 3
Part		THE FOLLOWING ATTACHMENT(S) ARE PART OF THIS ACTION:	
L. 3.		Notice of References Cited by Examiner, PTO-892. Notice of Art Cited by Applicant, PTO-1449 Notice of Art Cited by Applicant, PTO-1449 Notice of Informal Patent	PTO-946.
	_	Notice of Art Cited by Applicant, PTO-1449 4. Motics of Informal Patent / Information on How to Effect Drawing Changes, PTO-1474 6.	Application, Form PTO-152
Part		SUMMARY OF ACTION	,
- 21	II.	<u> </u>	
1.	4	Claims 1- / 8	are pending in the application.
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		Of the above, claims	are withdrawn from consideration,
2.		Claires	have been cancelled.
3,		Claims	are siloned.
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~			are rejected.
5.		Claims	are objected to.
6.		Claimsatt subject to pro-	striction or election requirement.
7.		This application has been filed with informal drawings which are acceptable for exemination oursesses	
		messi o morese.	
		Allowable subject matter having been indicated, formal drawings are required in response to this Diffice	
9. .		The corrected or substitute drawings have been received on These drawing not acceptable (see explanation).	s are [scceptable;
10.		The proposed drawing correction and/or the proposed additional or substitute sheet(s) of drawing (have) been approved by the examiner disapproved by the examiner (see explanation).	ngs, filed on
11.		The proposed drawing correction, filed, has been approved disapproved.	proved (see explanation). However,
		the Patent and Tradomark Office no longer makes drawing changes. It is now applicant's responsibility corrected. Corrections <u>MUST</u> be effected in accordance with the instructions sat forth on the attached EFFECT ORAWING CHANGES", PTO-1474.	to ensure that the drawings are letter "INFORMATION ON HOW TO
12.		Acknowledgment is made of the cizim for priority under 35 U.S.C. 119. The certified copy has [] bet	en received not been received
		been filed in parent application, serial no; filed on;	
13.		Since this application appears to be in condition for allowance except for formal matters, prosecution at accordance with the practice under Ex parte Quayle, 1935 C.D. 11; 453 O.G. 213.	to the merits is closed in
14.	П	Other	· •
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	P	TOL-326 (Rev. 7 - 82) EXAMINER'S ACTION	
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Serial No. 041,994 Art Unit

253

-2-

On page 9 line 28 "72" should be --73--. Claims 1, 2, 4-7, 16 are rejected under 35 U.S.C. 112, first and second paragraphs, as the claimed invention is not described in such full, clear, concise and exact terms as to enable any person skilled in the art to make and use the same, and/or for failing to particularly point out and distinctly claim the subject

The structure of claim I is indefinite. The language "being united in one structure" is vague and indefinite and does not clearly or concretely define the structure of applicant's invention. The terms "insulated gate FET" and "double sided JFET" are also broad and do not define applicant's invention. Claim 2 is confusing since lines 14-17 mimic lines 17-20. The other claims are rejected for dependence on 1 or 2.

matter which applicant regards as the invention.

The specification is objected to as failing to provide proper antecedent basis for the claimed subject matter. See 37 CFR 1.75(d)(1) and MPEP 608.01(o). Correction of the following is required: there is no proper antecedent in the specification for the process descriptions of claims 11, 13, 14, 17.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless-

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international .

Serial No. 041,994 Art Unit 253

-3-

application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

Claims 1-3, 5-9, 11, 12, 16 rejected under 35 U.S.C. 102(e) as anticipated by or, in the alternative, under 35 U.S.C. 103 as obvious over Colak.

Colak shows a DMOS device wherein layer 16 may perform the function of a JFET gate "on top of" an extended drain region 14 in the embodiment of figs. 2B or 2C. Substrate layer 12 may act as the other gate of the JFET. Clearly claim 1 does not distinguish over Colak. Note that mere labels as "JFET" do not structurally distinguish the claims over Colak since the structure of Colak may be labeled an IGFET in series with a double sided JFET as shown above. Claim 2 also does not distinguish over Colak since the claimed structure is shown in Colak and the intended use language "whereby current flow..." in claim 2 does not structurally distinguish over Colak and furthermore Colak's device may perform the same intended function. See In re Pearson 181 USPQ 642 or Ex parte Minks 169 USPQ 120 on statements of intended use in claims drawn to structure as we have here. Similarly claim 3 does not distinguish over Colak. Claim 5 is a product by process claim which does not structurally distinguish applicant's final product over Colak.

A "product by process" claim is directed to the product per se, no matter how actually made, In re Hirao, 190 USPQ 15 at 17 (footnote 3). See also In re Brown, 173 USPQ 685; In re Luck, 177 USPQ 523; In re

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-4-

Fessmann, 180 USPQ 324; In re avery, 186 USPQ 161; In re Wertheim, 191 USFQ 90 (209 USPQ 554 does not deal with this issue); and In re Marosi et al, 218 USPQ 289, all of which make it clear that it is the patentability of the final product per se which must be determined in a "product by process" claim, and not the patentability of the process, and that, as here, an old or obvious product produced by a new method is not patentable as a product, whether claimed in "product by Process" claims or not. Note that applicant has the burden of proof in such cases, as the above caselaw makes clear.

Claim 6 also is undistinguishing over Colak since the thickness of layer 16 is a design variable and 1 micron thickness would not be unobvious to one of ordinary skill in view of Colak. Similarly, in re claim 7 a dopant density of greater than 5x1016/cc would not be unobvious for the doping density of layer 16 of Colak. Claims 8, 9 also are obvious over Colak. Claims 11, 12 are product by process claims which also do not distinguish the final product over Colak. Claim 16 also does not distinguish over Colak as "floating" is vague and undistinguishing.

The following is a quotation of 35 U.S.C. "103 which forms the basis for all obviousness rejections set forth in this Office action:

A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Subject matter developed by another person, which qualifies as prior art only under subsection (f) and (g) of section 102 of this title, shall not preclude patentability under this section where the subject matter and the claimed invention were, at

Art Unit 253

the time the invention was made, owned by the same person or subject to an obligation of assignment to the same person.

Claims 4, 10, 13-15, 17 and 18 rejected under 35 U.S.C. 103 as being unpatentable over Colak in view of Thomas.

Thomas shows the obvious of providing low voltage and high voltage devices on the same substrate. It would be obvious from Thomas to practice Colak as CMOS or with other devices. Claim 4 is hence obvious. In re claims 10, 13, 15 "well" regions are also obvious from Thomas. Claims 14, 17 also are product by process claims which do not distinguish the final product over the suggestions of the references on final structure. Claim 18 also does not distinguish over the suggestions of Colak in view of Thomas.

Any inquiry concerning this communication should be directed to J. Jackson at telephone number 703-557-4824.

ackson/EW 12-2-87

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SUPERVISORY T EXAMINER GROUP ART WHIT 253

(Rev. 8-62)	FATENT AND TR	ADEMARK OFFICE	ATTACHMENT TO PAPER NUMBER
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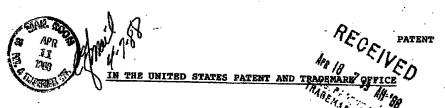
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Applicant : Klas H. Eklund

Serial No.: 07/041,994

Filed : 04-24-87

For

: HIGH VOLTAGE MOS TRANSISTORS

COMMISSIONER OF PATENTS & TRADEMARKS Washington, D.C. 20231

Date of this Paper:

Group Art Unit

Examiner: J. Jackson

Attorneys Docket No SS-520-01

April 7, 1988

AMENDMENT

In response to the U.S. Patent Office Action mailed December 7, 1987 (Paper No. 2), please amend this application as follows: In the Specification

Page 1, line 26, change "of" to --on--;

Page 9, line 15, insert the following paragraph:

-- It should be noted that the term "substrate" refers to the physical material on which a microcircuit is fabricated. If a transistor is fabricated on a well of n or p type material within a primary substrate of opposite type material, the well material can be considered a secondary substrate. Similarly, if a transistor is fabricated on an epitaxial layer or epi-island that merely supports and insulates the transistor, the epitaxial layer or epi-island can be considered a secondary substrate. An epi-island is a portion of an epitaxial layer of one conductivity type that is isolated from the remaining portion of the epitaxial layer by diffusion pockets of an . opposite conductivity type. When complimentary transistors are formed on the same chip, the well in which one complimentary transistor is embedded is formed by the same diffusion as the extended drain region for the other transistor .--

Add new claims 19-23 as follows:

A high voltage MOS transistor comprising:

a semiconductor substrate of a first conductivity type having a surface,

a pair of laterally spaced pockets of semiconductor material of a second conductivity type within the substrate and adjoining the substrate surface,

a source contact connected to one pocket, a drain contact connected to the other pocket, an extended drain region of the second conductivity type extending laterally each way from the drain contact pocket to surface-adjoining positions,

surface adjoining a layer of material of the first conductivity type on top of an intermediate portion of the extended drain region between the drain contact pocket and the surface-adjoining positions,

said top layer of material and said substrate being subject to application of a reverse-bias voltage,

an insulating layer on the surface of the substrate and covering at least that portion between the source contact pocket and the nearest surface-adjoining position of the extended drain region, 0 and

a gate electrode on the insulating layer and electrically isolated from the region thereunder which forms a channel laterally between the source contact pocket and the nearest surface-adjoining position of the extended drain region, said gate electrode controlling by field-effect the flow of current thereunder through the channel.

20. The high voltage MOS transistor of claim 19 having one channel conductivity type in combination with a complimentary high voltage MOS transistor of an opposite channel conductivity type combined on the same chip and isolated from each other.

21. The high voltage MOS transistor of claim 25 combined on the same chip with a low voltage CMOS implemented device.

The combination of claim 21 further including, -high voltage MOS transistor, and complementary low voltage CHOS implemented device on the same chip and isolated from each other.

23.7 A high voltage MOS transistor comprising:

a semiconductor substrate of a first conductivity type having a surface,

a pair of laterally spaced pockets of semiconductor material of a second conductivity type within the substrate and adjoining the substrate surface,

a source contact connected to one pocket,

an extended source region of the second conductivity type extending laterally each way from the source contact pocket to surface-adjoining position,

surface adjusted of the first conductivity type on top of a layer of material of the first conductivity an intermediate portion of the extended source region between the surface-adjoining positions,

said top layer and said substrate being subject to application of a reverse-bias voltage,

a drain contact connected to the other pocket,

in an extended drain region of the second conductivity type extending laterally each way from the drain contact pocket to a surface-adjoining positions,

a layer of material of the first conductivity type on top of an intermediate portion of the extended drain region between the drain contact pocket and the surface-adjoining positions,

said top layer of material and said substrate being subject to application of a reverse-bias voltage,

an insulating layer on the surface of the substrate and covering at least that portion between the nearest surface-adjoining positions of the extended source region and the extended drain region, and

a gate electrode on the insulating layer and electrically isolated from the region thereunder which forms a channel laterally between the nearest surface-adjoining positions of the extended source region and the extended drain region, said gate electrode controlling by field-effect the current flow thereunder through the channel.

Amend the claims as follows:

Claim 6, line 1, change "5" to -- 19--; and

Claim 7, line 1, change "5" to -- 19--.

REMARKS

The specification has been amended to correct minor errors and to provide an antecedent basis in the specification for epitaxial layer and epi-island mentioned in former claims 11 and 13.

This invention relates to high voltage, metal oxide semiconductor transistors of the field effect type. There is a need for more efficient transistors which can be made as either discrete or integrated devices of either n-channel or p-channel conductivity.

integrated devices should be easily combined with low voltage (five. volt) control logic on the same chip. Devices of opposite conductivity should be combinable in a complimentary manner on the same chip. Such transistors, with modifications, should be capable of source-follower applications.

The applicant has disclosed a novel and unobvious high voltage MOS transistor having a low threshold voltage that is compatible with five volt control logic and a low ON-resistance. This transistor can be made as either discrete or integrated devices of either n-channel or p-channel conductivity. The high voltage MOS transistors can be modified for source-follower applications by providing both extended source regions and extended drain regions. These transistors are formed on a substrate of a first conductivity type having a surface. A pair of laterally spaced pockets of semiconductor material of a second. conductivity type are provided within the substrate and adjoining the substrate surface. A source contact is connected to one pocket and a drain contact is connected to the other pocket. An extended drain region of a second conductivity type extends laterally each way from the drain pocket to surface-adjoining positions. A layer of material of the first conductivity type is provided on top of an intermediate portion of the extended drain region between the drain contact pocket and the surface-adjoining positions. The top layer of material and the substrate are subject to application of a reverse-bias voltage. None of the cited references show such structure.

Colak, U.S. Patent No. 4,626,879, shows a DMOS transistor suitable for source follower applications. This device has a substrate with three epitaxial layers formed thereon. A surface-adjoining channel region is diffused into the epitaxial layers and a source region is diffused into the channel diffusion above the channel region. A drain region is diffused into the top epitaxial layer. An extended drain

region is formed from a portion of the top epitaxial layer between the drain region and the channel region. The top and bottom epitaxial layers are interconnected, and the bottom layer may operate as a parallel extended drain region between the connection points. The intermediate epitarial layer may operate as an extended drain region in a dual-gate/dual-drain structure wherein all three epitaxial layers contribute to device conductivity for achieving optimum normalized "ON" resistance.

Thomas, U.S. Patent No. 4,628,341 shows an integrated circuit structure that includes both low-voltage n-channel and p-channel MOS transistors and high voltage n-channel and p-channel MOS transistors.

The claims are now clearly distinguished from the cited references. New claim 19 recites "an extended drain region of the second conductivity type extending laterally each way from the drain contact pocket to surface-adjoining positions, a layer of material of the first conductivity type on top of an intermediate portion of the extended drain region between the drain contact pocket and the surface-adjoining positions". When high voltage n-channel and p-channel devices are combined on the same chip with low voltage control logic, this structure isolates the devices from each other. Claim 19 also provides for a pair of laterally spaced source and drain contact pockets within the substrate as is customary for conventional MOS transistors and is thus, distinguished from DMOS devices which require a higher threshold voltage. The structure of claim 19 enables a lower threshold voltage, compatibility with five volt control logic, and eliminates the need for an additional power supply and interface circuit.

Claims 20-22 and claims 6-7 depend directly or indirectly from claim 19 and thus, can be distinguished for the same reasons as claim 19_

Claim 23 is directed to the transistor, shown in Fig. 5 of the drawings, that has been modified for source-follower applications by providing both extended source and drain regions. Top layers cover intermediate portions of the extended source and drain regions. The top layers and substrate are subject to application of a reverse-bias voltage.

Accordingly, claims 6-7 and 20-23 are patentably distinct from the cited references and allowance of these claims is requested.

If the Examiner is of the opinion that a telephone conference with applicant's attorney would expedite matters, such a conference is invited.

Respectfully submitted,

Reg. No. 22,611

Thomas E Schatzel

LAW OFFICES OF THOMAS E. SCHATZEL A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, California 95054 Telephone: (408) 727-7077

I hereby cariffy that this correspondence is being deposited with the United States Fostel Service as first class mail in an exvelope addressed ter Commissioner of Patents and Tradements, Wash-

agion, D.C. 20231, on <u>4-7-88</u>

Filed: 14-24-87	PATENT
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CONDITIONAL PETITION FOR EXT	TENSION OF TIME
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NOTE: Please also char	rge issues fees under 37 C.F.R. 1.1
to Account No. 19-0310.	•
Reg. No. 22,611	Attorney for Applicant
Telephone: {408} 727-7077	Law Offices of Thomas E. Schatze
I hereby certify that this correspondence is being depended with the United States Richal Service on first clear mail in an arrescope addressed test Commissioner of Patents and Trademonia, Washington, D.C. 2021; on 47–788 [Date of Reposit) Thomas E. Schatzel Nerry of applicant facility p. indicated for the commission.	3211 Scott Boulevard, Suite 201 Santa Clara, California 95054
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Art Unit 253

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless-

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invantion thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

Claims 19, 6, 7 are rejected under 35 U.S.C. 102

(a) as anticipated by or, in the alternative, under 35

U.S.C. 103 as obvious over Colak.

Claim 19 still does not distinguish over Colak. See figures 1, 28 and 2C of Colak where 22 and 24 define "pockets", layers 18 and 14 form an "extended drain" which extends to the surface "each way" from the drain contact 24, layer 16 defines a layer of material of first conductivity type "on top of" extended drain layer 14, and layer 16 and substrate 12 are subject to application of a reverse bias voltage during operation of the device. Note that layer 16 is connected to the source and the substrate is reverse biased through SS. Thus claim 19 does not distinguish over Colak. undistinguishing since Colak teaches a layer 16 thickness of 2 micron for 400 V operation, however, for lower voltage operation design layer 16 would be thinner, and 1 micron thickness is thus an obvious design variant to the artist. Similarly, to the artist, the design of claim 7 is obvious in view of Colak who teaches 1016/cm3 for layer 16.

Art Unit 253

The following is a quotation of 35 U.S.C. 103 which forms the basis for all obviousness rejections set forth in this Office action:

A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the sub-ject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was

Subject matter developed by another person, which qualifies as prior art only under subsection (f) and (g) of section 102 of this title, shall not preclude patentability under this section where the subject matter and the claimed invention were, at the time the invention was made, owned by the same person or subject to an obligation of assignment to the same person.

Claims 20-23 are rejected under 35 U.S.C. 103 as being unpatentable over Colak in view of Thomas.

As stated in the previous rejection, Thomas shows that high voltage fet devices (as Colak) are advantageously formed complementary and also integrated with low voltage devices. Hence claims 20-22 are obvious.

Claim 23 is rejected under 35 U.S.C. 103 as being unpatentable over Sze.

Colak teaches punch through and avalanche protection layer 16 for a DMOS device. To one of ordinary skill it would have been obvious to practice the teachings of Colak in other MOS devices as ordinary fets as shown in Sze. Note figures 3, 51 or 52 of Sze where the source or drain are structurally similar and their function is dependent on the particular voltage applied. Hence, to the artist it would be obvious to apply the

Art Unit 253

teachings of Colak to symmetrical ordinary fets as shown in Sze to provide higher voltage operation.

Document 596-2

Applicant's arguments filed April'11, 1988 have been fully considered but they are not deemed to be persuasive.

Applicant's argument that Colak does not show a drain "extending laterally each way" from the drain is not convincing as shown in the above rejustion.

Clearly there is drain material 18 on each side of pocket 24.

Applicant's amendment necessitated the new grounds of rejection. Accordingly, THIS ACTION IS MADE FINAL. See MPEP 706.07(a).

Applicant is reminded of the extension of time policy set forth in 37 CFR 1.136(a). The practice of automatically extending the shortened statutory period an additional month upon the filing of a timely first response to a final rejection has been discontinued by the Office. See 1021 TMOG 35.

A SHORTENED STATUTORY PERIOD FOR RESPONSE TO THIS PINAL ACTION IS SET TO EXPIRE THREE MONTHS FROM THE DATE OF THIS ACTION. IN THE EVENT A FIRST RESPONSE IS FILED WITHIN TWO MONTHS OF THE MAILING DATE OF THIS FINAL ACTION AND THE ADVISORY ACTION IS NOT MAILED UNTIL AFTER THE END OF THE THREE-MONTH SHORTENED STATUTORY PERIOD, THEN THE SHORTENED STATUTORY PERIOD WILL EXPIRE ON THE DATE THE ADVISORY ACTION IS MAILED, AND ANY EXTENSION PEE PURSUANT TO 37 CFR 1.136(a) WILL BE CALCULATED FROM THE MAILING DATE OF THE ADVISORY ACTION. IN NO EVENT WILL THE STATUTORY PERIOD FOR RESPONSE EXPIRE LATER THAN SIX MONTHS FROM THE DATE OF THIS FINAL ACTION.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to J. Jackson whose telephone number is (703) 557-4824.

Any inquiry of a general nature or relating to the status of this application should be directed to the Group receptionist whose telephone number is (703) 557-3311.

Q J. Jackson:klw

6-15-88

(703) 557-4824

SUPERVISORY AT UNIT EXAMINER
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Klas H. Eklund

Group Art Unit: 253

Serial No.: 07/041,994

Examiner: J. Jackson, Jr.

: April 24, 1987

Attorneys Docket No.: 55 SS-520-01

: HIGH VOLTAGE MOS TRANSISTORS

ATTENTION: BOX A.F.

COMMISSIONER OF PATENTS &.TRADEMARKS Washington, D.C. 20231

Date of this Paper:

August 12, 1988

AMENDMENT AFTER FINAL

In response to the U.S. Patent Office Action mailed June 17, 1988 (Paper No. 4), please amend this application as follows:

In the Claims

Claim 19, line 12, before "layer" insert --surface adjoining--;

line 22, before "region" insert -- substrate--.

Claim 20, line 2, change "complimentary" to --complementary--

Claim 22, line 2, change "complimentary" to --complementary

line 3, change "complimentary" to --complementary--.

Claim 23, line 9, delete "a";

line 10, change "position" to --positions-

line 11, before "layer" insert --surface adjoining--;

line 18, delete "a";

line 20, before "layer" insert .-- surface adjoining--;

line 30, before "region" insert -- substrate--.

REMARKS

The applicant appreciates the telephone interview on August 10, 1988, courteously granted by the Examiner.

Claim 19, as amended, now provides for an extended drain region of the second conductivity type extending laterally each way from the drain contact pocket to surface-adjoining positions and a surface adjoining layer of material of the first conductivity type on top of an intermediate portion of the extended drain region between the drain contact pocket and the surface-adjoining positions. The layer 16 of Colak is not surface-adjoining but is buried under layer 18. There is no layer of material of the first conductivity type on top of layer 18. Colak's layer 16 extends from beneath the drain contact pocket 24 to the channel region 20, and thus, is not between the drain contact pocket and the surface adjoining positions of the extended drain region.

Claim 19 also provides for the top layer of material and the substrate being subject to application of a reverse-bias voltage.

Thus, the top layer and the substrate act as gates for controlling current flow through the extended drain region between the surface adjoining positions and the drain contact pocket. This structure can be considered a double-sided, junction-gate field-effect transistor (JFET). Colak shows a layer 14 intermediate a layer 16 and a substrate 12 that are subject to application of a reverse-bias voltage. Though this structure of Colak could be considered a double-sided JFET, layer 16 is not surface-adjoining as defined in claim 19. Colak's double-sided JFET is buried under layer 18 which is connected in parallel with layer 14 by semiconductor zones 16c, 16d. Layer 16 also acts as a gate for layer 18 so that layers 16 and 18 could be considered a single-sided JFET. Thus, the extended drain of Colak includes the single-sided JFET connected in parallel with the double-

sided JFET thereunder. Both the extended drain structure of claim 19 and Colak's drain structure have relatively high voltage capability. However, it is desirable to control the high voltage with relatively low voltage.

Claim 19 further provides for a substrate having a surface, an insulating layer on the surface of the substrate covering at least that portion between the source contact pocket and the nearest surfaceadjoining position of the extended drain region, and a gate electrode on the insulating layer electrically isolated from the substrate region thereunder which forms a channel laterally between the source contact pocket and the nearest surface-adjoining position of the extended drain region. Thus, claim 19 is limited to a MOS or MOSFET structure, while Colak shows a D-MOS device. The MOSPET structure has a lower threshold voltage than a D-MOS device (0.7 volts compared to two - four volts for the D-MOS device) and thus, is directly compatible with five volt logic. D-MOS devices usually require an additional power supply of ten to fifteen volts for driving the gate. The MOSPET structure has less on-resistance and thus, further reduces the total on-resistance of the combined structure (MOSPET plus double-sided JFET).

Claim 19 is directed to the structural combination of a double-sided JFET and a MOSFET so that a high voltage transistor can be controlled with relatively low voltage. Thus, claim is is patentably distinct over Colak.

Claims 20-22 and claims 6-7 depend directly or indirectly from claim 19 and are thus patentably distinct from Colak for the same reasons as claim 19. While Thomas shows that high voltage FET devices are advantageously formed complementary and also integrated with low voltage devices, claims 20-22 are limited to transistors having the structure as defined in claim 19. This structure facilitates isolation of complementary high voltage devices and low voltage, C-MOS

implemented devices on the same chip. Isolation of the epitaxial layers shown by Colak from corresponding layers of a complementary device would be difficult.

Claims 6 and 7 include further limitations on the depth of the top layer and the doping density thereof. The depth is one-half or less than that disclosed by <u>Colak</u> for layer 16 and the doping density is at least five times greater. Furthermore, <u>Colak's</u> layer 16 is not similarly situated as the top layer of claim 19, and thus, is not comparable. Thus, claims 6 and 7 are patentably distinct from <u>Colak</u> for the same reasons as claim 19 and for the further limitations therein.

Claim 23 is directed to the transistor 63; shown in Fig. 5, that is suitable for source follower applications. This claim contains limitations similar to claim 19 for the MOSFET structure and the double-sided JFET about the drain contact pocket. It further includes structural limitations for a double-sided JFET about the source contact pocket. While the book by Sze discloses MOSFET structures having sources and drains that are similar to each other, such sources and drains are not similar to the double-sided JFET structures disclosed by the applicant and specifically claimed structurally in claim 23. Thus, claim 23 is patentably distinguished from Sze.

Should the Examiner be of the opinion that a telephone conference with applicant's attorney would be beneficial, he is invited to contact the undersigned at the number set out below.

Respectfully submitted,

Reg. No. 22,611

LAW OFFICES OF THOMAS E. SCHATZEL A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, California 95054 Telephone: (408) 727-7077

PATENT

CONDITIONAL PETITION FOR EXTENSION OF TIME

If any extension of time for this response is required applicant requests that this be considered a petition therefor.

Status This application is on behalf of: other than a small entity verified statement attached small entity verified statement already

Payment of fees

x The Commissioner is hereby authorized to charge any additional fees as set forth in 37 C.F.R. 1.16 and 1.17 which may be required or credit any overpayment to Account No. 19-0310. A duplicate of this transmittal is attached.

filed

NOTE: Please charge issues fees under 37 C.F.R. 1.18 do not to Account No. 19-0310.

22,611 Reg. No.

Telephone: (408) 727-7077

Law Offices of Thomas B. Schatzel A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, California 95054



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herwith (or previously melled), a Notice Of Allowar	THE MEXITS IS (OR REMAINS) CLOSED in this application. If not included toe And besse Pee Due or other appropriate communication will be sent in due						
1. 85 The slowed claims are 6,7, 19-23	·						
4. The drawings filed on are accordable.							
	under 35 U.S.C. 118. The certified copy has [_] been received. [_] not been						
received. [] been filed in perent application Serial No	under 25 U.S.C. 116. The cortined copy has [] been received. [] not been						
6. D Note the attached Examiner's Amendment.	**************************************						
7. Note the attached Examiner Interview Summary Reco	w4 9701_419						
8. C Note the attached Examiner's Statement of Reasons							
9. Note the attached NOTICE OF REFERENCES CITED.							
10. I Note the attached INFORMATION DISCLOSURE CITA							
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FROM THE "DATE MAILED" Indicated on this form, Fall Extensions of time may be obtained under the provisions of 3	comply with the requirements noted below is set to EXPIRE THREE MONTHS have to timely comply will result in the ABANDONMENT of this application. 7 GPA 1.19(a).						
OF declaration is deficient. A SUBSTITUTE OATH OF D	OTICE OF INFORMAL APPLICATION, PTO-152, which discloses that the only ECLAPATION IS REQUIRED. I INDICATED BELOW IN THE MANNER BET FORTH ON THE REVERSE SIDE						
OF THIS PAPER.							
	TICE RE PATENT DRAWINGS, PTO-846, attached hereto or to Paper No.						
b. [] The proposed drawing correction filed on REQUIRED.	has been approved by the examiner. CORRECTION IS						
 Approved drawing corrections are described by the examiner in the attached EXAMINER'S AMENDMENT, CORRECTION IS REQUIRED. 							
d. 🗍 Formal drawings are now REQUIRED.							
Any response to this letter should include in the upper rigitant RESIDE BATCH NUMBER, DATE OF TH	hi hand corner, the following information from the NOTICE OF ALLOWANCE ENOTICE OF ALLOWANCE, AND SERIAL NUMBER.						
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NOTICE OF ALLOWANCE AND ISSUE FEE DUE

THOMAS E. SCHATZEL 3211 BCOTT SLVD., STE. 201 SANTA CLARA, CA 95054-3093 All communications regarding this application should give the serial number, date of filing, name of applicant, and batch number.

Please direct all communications to the Attention of "OFFICE OF PUBLICATIONS" unless advised to the contrary.

The application identified below has been examined and found allowable for lessuance of Letters Pasent. PROSECUTION ON THE MERETS IS CLOSED.

	SC/SERIAL NO.	FILING DATE	TOTAL CLAMS	EXAMINER AND GROUP ART UNIT		DATE MARLED
	07/041,994	04/24/87	007	JACKBON JR. J	253	08/25/B8
First Named Applement	EKLUND,		KLAI	в н.		

TITLE OF

HIGH VOLTAGE MOB TRANSISTORS

ATTY'S DOCKET NO.	CLASS-SUBCLASS	BATCH NO.	APPLN. TYPE	SMALL ENTITY	FEE DUE	DATE DUE
\$6-520-01	357-046-000	L46	UTILITY	YES	\$280.00	11/25/88

The amount of the issue see is specified in 37 C.F.A. 1.18. If the applicant qualified for and has field a verified statement of small entity attents in accordance with 37 C.F.R. 1.27, the issue see is one-helf the amount for non-small entities. The issue fee due printed above reflects applicant's states as of the time of making this notice. A verified statement of small entity states may be filed prior to or with payment of the issue see. However, in accordance with 37 C.F.R. 1.28, felter to establish status as a small entity prior to or with payment of the issue see precludes payment of the issue see in the amount so established for small entities and practices a refund of any portion thereof paid prior to establishing

stess as a small entity.

THE ISSUE PEE MIST BE PAID WITHIN THREE MONTHS FROM THE MAILING DATE OF THIS NOTICE as indicated above. The application shall otherwise be regarded as ABANDONED. The issue fee will not be accepted from anyone other than the applicant; a registered attorney or agent; or the assignee or other party in interest as shown by the records of the Patent and Trademark. Office. Where an authorization to charge the issue fee to a deposit account has been filled before the mailing of the notice of allowance, the last fee is charged to the deposit account at the time of mailing of this notice in accordance with 37 C.F.R. 1.311. If the issue fee has been so charged, it is indicated above.

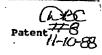
In order to minimize delays in the issuence of a patent based on the application, this Notice may have been mailed polar to completion of final processing. The nature and/or extent of the remaining ravision or processing requirements may cause sight delays of the patent. In addition, if prosecution in the be reopened, this Notice of Allowance will be vacated and the appropriate Office actions will follow be delegated to the patent of the patent o

In the case of each patent issuing without an essignment, the complete post office address of the inventorie) will be printed in the petent heading and in the Official Geratte. If the inventor's address is now different from the address which appears in the application, please fill in the information in the spaces provided on PTOL-85b anclosed. If there are address changes for more than two inventors, enter the addresses on the reverse side of the PTOL-85b.

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De l	or at least 10 copies and must accompany the issue fee. The copies	ordered will be sent only to the address specified in section 1 or 1A or
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	This notice is issued in view of applicant's communication filed	Peteris issuing on applications filed on or after Dec. 12, 1980 may require payment of maintenance fees, See 37 CFI 1.20 [4] — [8].
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Bklund, Klass H.

Filed 04/24/87

Examiner Jackson Jr., Issue Batch No.: L66

Allowance Date 08/25/88

Serial No. : 07/041,994

Group Art Unit: 253

Atty Docket No.: SS-520-01

For

: "HIGH VOLTAGE MOS TRANSISTORS"

Box Issue Fees COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D. C. 20231 Date of This October 19,

FORMAL DRAWING TRANSMITTAL

Transmitted herewith are formal drawings for the above identified application as requested in the Notice of Allowance, Paper No. 7, mailed August 25, 1988. Corrections have been made as requested by the Examiner. Applicant respectfully requests that the formal drawings be filed.

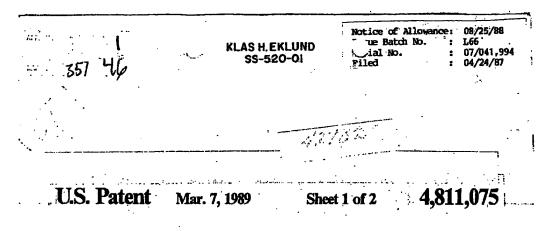
Respectfully submitted,

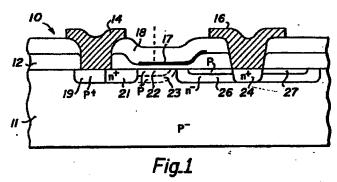
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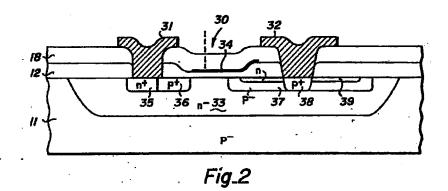
Attorney for Applicant

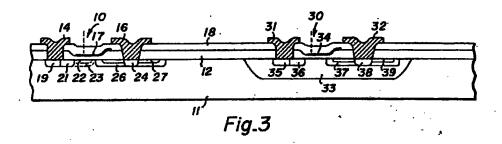
LAW OFFICES OF THOMAS E. SCHATZEL A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, CA 95054-3093

Telephone: (408) 727-7077









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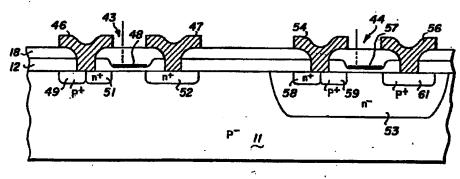
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Notice of Allowance: 08/25/88 Jesue Batch No. ial No. L66 07/041,994

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Mar. 7, 1989

Sheet 2 of 2



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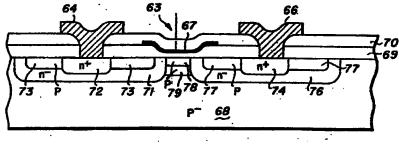


Fig.5



Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Eklund, Klas H.

Issue Batch No.: L66

Filed

- 04/24/87

Allowance Date 08/25/88

Bxaminer : Jackson Jr., J.

Serial No.

: 07/041,994

Group Art Unit : 253

Atty Docket No.: SS-520-01

: "HIGH VOLTAGE MOS TRANSISTORS"

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Date of This Paper

October 19, 1988

PAYMENT OF ISSUE PER (37 CFR 1.311)

- 1. Applicant hereby pays the issue fee.
- Fee (37 CFR 1.18(a))

Application status is:

X small entity-

fee \$ 280.00

X Verified Statement attached

_____ Verified Statement filed

other than small entity-

fee \$ 560.00

Payment of fee

X Enclosed please find check 11177 for \$302.00 *

__ Charge Deposit Account 19-0310 the sum

of \$ ____. A duplicate of this request

is attached.

* Includes Advance Order and Assignment Recordal Fee

Respectfully submitted

Attorney for Applicant

Law Offices of THOMAS E. SCHATZEL A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, CA 95054-3093 Telephone: (408) 727-7077

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Klaus H. Eklund: Title: Vice President, Engineering

88-510-01 POWER OF ATTORNEY BY ASSIGNEE The subject matter which is described and claimed and for which a patent is sought on the invention entitled: HIGH VOLTAGE MOS TRANSISTORS the specification of which is attached hereto; X was filed on April 24, 1987 ss Application Serial No. 07/041,994 and was emended on 04/11/88; 08/15/88 (if applicable) Assignment recorded on at Reel/Frame (if applicable) hereby elects to control the prosecution of this application and hereby appoints the following attorneys(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office in connection therewith: Thomas E. Schatzel Reg. No. 22,611 Address all correspondence to: LAN OFFICES OF THOMAS E. SCHATZEL A Professional Corporation 3211 Scott Boulevard, Suite 201 Santa Clara, California 95054-3093 Address all telephone calls to Thomas E. Schatzel at telephone No. (408) 727-7077. Assignes hereby petitions and requests that this file be closed to the inventor(s), or representative(s) thereof. POWER INTEGRATIONS, INC.

POWER INTEGRATIONS, INC. 411 Clyde Avenue Hountain View, California



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4. The assignee in this application has intervened and appointed an attorney of his own scientism. Further correspondence
will be held with mid attentory. (Rule 36, Rules of Fractica.)
5. The reveration of the power of attorney to
entered and said attorney has been setified. Further correspondence will be addressed to you.
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6. On the applicant appointed
as additional attorney in this application. Further correspondence will continue to be addressed to you as
specified in the new power of attorney.
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7. Cu, the applicant appointed
as additional atterney in this application. Further correspondence will be addressed to mid attenny. MPEP 403.02
8. The associate power of attorney to you in this application has been revoked by the attorney of record.
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Attorney Docket No.: SS-520-01

PATENT & TRADEMARK OFFICE PATENT

IN THE UNITED STATES PATENT ANIT TRADSMARK OFFICE

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PATENT MAINTENANCE DIVISION

Granted: Inventor(s):

03/07/89

Klas H. Eklund

Box: Patent Address Change Commissioner of Patents and Trademarks Washington, D.C. 20231

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CHANGE OF CORRESPONDENCE ADDRESS IN PATENT

1. Change the address of the attorney(s) of record to:

Thomas E. Schatzel, Esq. LAW.OFFICES OF THOMAS E. SCHATZEL

	2. Change the correspondence addres	A PROFESSIONAL CORPORATION 16400 LARK AVENUE, SUITE 300 LOB GATOS, CA 95032
	z. Grange are conceptionalise actives	S on the placest owners to:
	It is certified that the person whose the correspondence address for the pa	signature appears below has the authority to change tent.
	Date: 05/03/93 LAW OFFICES OF. THOMAS E. SCHATZEL. A PROFESSIONAL CORPORATION 16400 LARK AVENUE, SUITE 300 LOS GATUS, GA. 95032 Tel. No.: (408) 358-7733	(Signature) THOMAS E SCHATZEL inventor(s) Assignee of complete interest Attorney or agent of record
	Reg. No.: 22,611 (il applicable)	- surely certify that this correspondence is too-deposited with the United States Postel Service at little class mail in se serviceps addressed to: Commissioner of Palents and Trademarks, West-
16400 LA	. SCHATZEL RK AVENUE, STE. 300 S, CA 95032	Ington, D.C. 20231, on 05/03/93 [Date of Deposition of De

(Change of Correspondence Address in Patent [12-6])